

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Currently amended) A method for inspecting semiconductor devices comprising:
~~based on a product name and a process name inputted through a terminal,~~
~~automatically accessing a design database by a computer processor via a communication means to download chip matrix data and chip size data;~~
~~automatically setting, by using design information, an inspection condition,~~
~~which differs in a comparing method and a threshold level based on a unit size of repeated patterns formed on a semiconductor device by said computer processor using the downloaded chip matrix data and chip size data;~~
~~inspecting at least one of the semiconductor device with an optical inspection tool to detect defects under devices with said inspection condition set by using said design information;~~
~~classifying said detected defects and outputting information of classified defect with information on whether said defect is on an optically transparent film or not;~~
~~automatically revising said inspection condition by said computer processor using data obtained by the inspecting; and~~
~~inspecting the another semiconductor device devices using said revised inspection condition.~~
2. (Previously presented) The method for inspecting semiconductor devices according to claim 1, wherein said inspection condition comprises information whether or not an area for inspection is in an area in which false alarms tend to occur.
3. (Currently amended) The method for inspecting semiconductor devices according to claim 1, further comprising controlling a pitch of a spatial filter which cuts off light diffracted from patterns formed on said semiconductor device wherein said

~~inspection condition is revised during said revising so that only actual foreign matter is detected or a false alarm rate is less than a preset amount.~~

4. (Currently amended) A method for inspecting semiconductor devices comprising:

~~based on a product name of a semiconductor device product name and names of processes used to process said product inputted through a terminal, automatically accessing a design database by a computer processor via a communication means to download chip matrix data and chip size data;~~

~~automatically setting inspection conditions by using design information of a semiconductor device said computer processor using said downloaded chip matrix data and chip size data;~~

~~inspecting at least one of the semiconductor device to detect defects devices with said inspection conditions;~~

~~classifying defects detected by inspecting said semiconductor device; and~~

~~automatically revising said inspection conditions by said computer processor using data obtained during the inspecting;~~

~~inspecting the semiconductor devices using said revised inspection conditions;~~
and

~~outputting results of the inspecting of the semiconductor devices by adding information on whether said detected defect is on an optically transparent film or not.~~

5. (Previously presented) The method for inspecting semiconductor devices according to claim 4, wherein said inspection conditions set at said setting comprises information whether or not an area to be inspected is in an area in which false alarms tend to occur.

6. (Currently amended) The method for inspecting semiconductor devices according to claim 4, ~~wherein~~ further comprising revising said inspection conditions set at said setting ~~are revised at said revising~~ so that only actual foreign matter is detected or a false alarm rate is less than a preset amount.

7. (Currently amended) A method for inspecting semiconductor devices comprising:

~~based on a product name and a process name inputted through a terminal, automatically accessing a design database by a computer processor via a communication means to download chip matrix data and chip size data;~~

automatically setting semiconductor device inspection conditions by using design information and said inspection condition which differs in a comparing method and a threshold level based on a unit size of repeated patterns formed on a semiconductor device
~~said computer processor using the downloaded chip matrix data and chip size data;~~

detecting defects by inspecting semiconductor devices using said set inspection conditions with an optical inspection tool;

~~classifying defects detected at said detecting as disposed in a transparent film or a non-transparent film by using the downloaded chip matrix data and chip size data;~~

~~automatically revising said set inspection conditions by said computer processor using classification results; and~~

outputting a result of said detecting by adding information on whether or not said detected defect is possible to review by SEM.

~~inspecting semiconductor devices using said revised set inspection conditions.~~

8. (Original) The method for inspecting semiconductor devices according to claim 7, wherein images of said classified defects are displayed on a screen.

9. (Canceled)

10. (Currently amended) The method for inspecting semiconductor devices according to claim 7, further comprising revising said set inspection condition by

using information of said classified defects ~~wherein, in said setting said set inspection conditions, semiconductor device design data is used.~~

11. (Canceled)

12. (Canceled)

13. (Canceled)

14. (Currently amended) A method for inspecting a semiconductor device comprising:

~~based on a received identifier for the semiconductor device, automatically accessing a design database by a computer processor to download design data;~~

~~automatically setting inspection conditions for [[the]] a semiconductor device using the downloaded design information data;~~

~~inspecting said semiconductor device for defects with under said set inspection conditions by using an optical inspection tool;~~

~~automatically generating revised inspection conditions based on results of said inspecting;~~

~~inspecting said semiconductor device for defects with said revised inspection conditions; and~~

~~classifying defects detected at said inspecting detecting as disposed in a transparent film or a non-transparent film,~~

~~wherein at least one of the inspection conditions is distinctly set for each area of the semiconductor device to be inspected, and~~

~~wherein said automatically setting is performed without capturing an image of an actual wafer said classifying comprises providing information on whether said detected defects are on an optically transparent film or optically non-transparent film.~~

15. (Currently amended) The method of claim 14 further comprising revising said inspection conditions set by using said design information wherein the design database is a physically remote design database.

16. (Canceled)

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PATENT

17. (Canceled)

18. (Canceled)

19. (Canceled)

20. (Canceled)